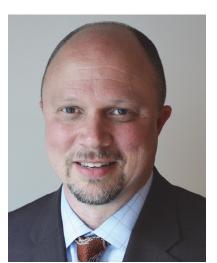# EDFAS 2016-2017 BOARD OF DIRECTORS

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